

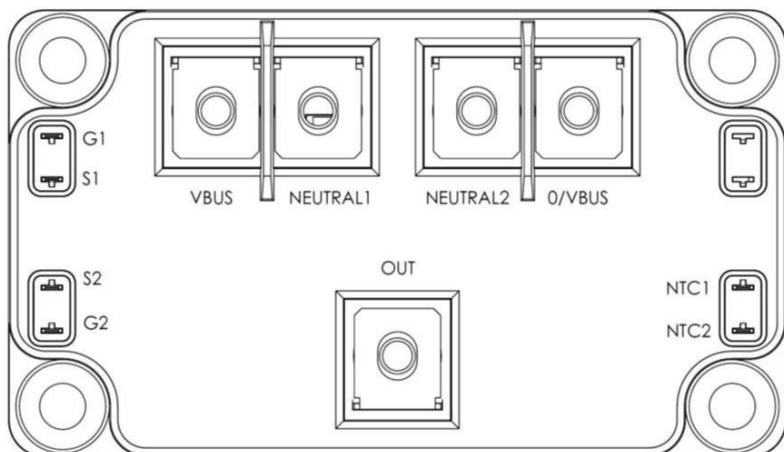
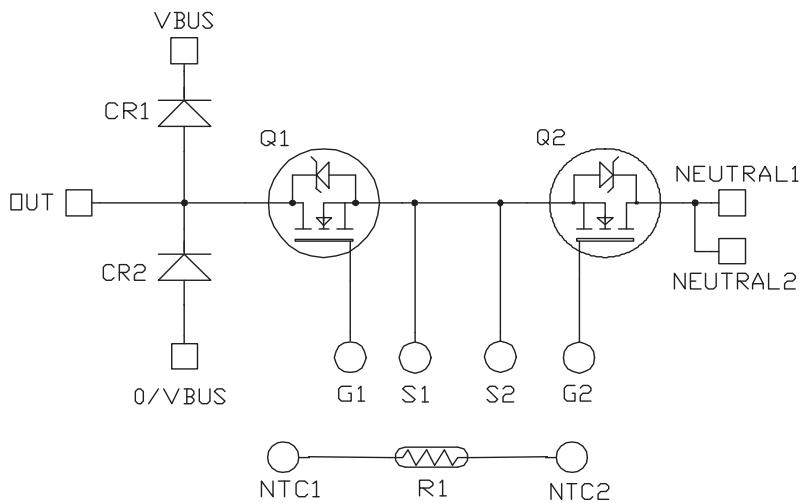


# MSCSM120VR1M062CT6AG

## Vienna Rectifier SiC MOSFET Power Module

### Product Overview

The MSCSM120VR1M062CT6AG device is a Vienna rectifier 1200V, 420A silicon carbide (SiC) power module.



**Note:** All ratings at  $T_J = 25^\circ\text{C}$ , unless otherwise specified.



These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

## **Features**

The following are the key features of MSCSM120VR1M062CT6AG device:

- SiC Power MOSFET
  - Low  $R_{DS(on)}$
  - High temperature performance
- SiC Schottky Diode
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature independent switching behavior
  - Positive temperature coefficient on  $V_F$
- Kelvin source for easy drive
- Low stray inductance
- M5 power connectors
- Internal thermistor for temperature monitoring
- Aluminum Nitride (AlN) substrate for improved thermal performance

## **Benefits**

The following are the benefits of MSCSM120VR1M062CT6AG device:

- Outstanding performance at high frequency operation
- High-power and high-efficiency rectifiers and converters
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Low profile
- RoHS compliant

## **Applications**

The following are the applications of MSCSM120VR1M062CT6AG device:

- Power factor correction
- Switched mode power supplies
- Uninterruptible power supplies

## 1. Electrical Specifications

The following sections show the electrical specifications of the MSCSM120VR1M062CT6AG device.

### 1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings (per SiC MOSFET) of the MSCSM120VR1M062CT6AG device.

**Table 1-1. Absolute Maximum Ratings**

Symbol	Parameter	Maximum Ratings		Unit
$V_{DSS}$	Drain-Source voltage	1200		V
$I_D$	Continuous drain current	$T_C = 25\text{ }^\circ\text{C}$	420	A
		$T_C = 80\text{ }^\circ\text{C}$	334	
$I_{DM}$	Pulsed drain current	840		
$V_{GS}$	Gate-Source voltage	−10/23		V
$R_{DS(on)}$	Drain-Source ON resistance	6.2		$\text{m}\Omega$
$P_D$	Power dissipation	$T_C = 25\text{ }^\circ\text{C}$	1753	W

The following table lists the electrical characteristics (per SiC MOSFET) of the MSCSM120VR1M062CT6AG device.

**Table 1-2. Electrical Characteristics**

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{V}; V_{DS} = 1200\text{V}$		—	50	500	$\mu\text{A}$
$R_{DS(on)}$	Drain-Source on resistance	$V_{GS} = 20\text{V}$	$T_J = 25\text{ }^\circ\text{C}$	—	5	6.2	$\text{m}\Omega$
		$I_D = 200\text{A}$	$T_J = 175\text{ }^\circ\text{C}$	—	8	—	
$V_{GS(th)}$	Gate threshold voltage	$V_{GS} = V_{DS}; I_D = 15\text{ mA}$		1.8	2.8	—	V
$I_{GSS}$	Gate-Source leakage current	$V_{GS} = 20\text{V}; V_{DS} = 0\text{V}$		—	—	500	nA

# MSCSM120VR1M062CT6AG

## Electrical Specifications

The following table lists the dynamic characteristics (per SiC MOSFET) of the MSCSM120VR1M062CT6AG device.

**Table 1-3. Dynamic Characteristics**

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0V$ $V_{DS} = 1000V$ $f = 1\text{ MHz}$	—	15.1	—	—	nF
$C_{oss}$	Output capacitance		—	1.4	—	—	
$C_{rss}$	Reverse transfer capacitance		—	0.13	—	—	
$Q_g$	Total gate charge	$V_{GS} = -5V/20V$ $V_{Bus} = 800V$ $I_D = 200A$	—	1160	—	—	nC
$Q_{gs}$	Gate-source charge		—	205	—	—	
$Q_{gd}$	Gate-drain charge		—	250	—	—	
$T_{d(on)}$	Turn-on delay time	$V_{GS} = -5V/20V$ $V_{Bus} = 600V$ $I_D = 250A$	—	56	—	—	ns
$T_r$	Rise time		—	55	—	—	
$T_{d(off)}$	Turn-off delay time		—	166	—	—	
$T_f$	Fall time	$T_J = 150\text{ }^{\circ}\text{C}$ $R_{GON} = 1.6\Omega$ $R_{GOFF} = 0.9\Omega$			67	—	
$E_{on}$	Turn-on energy		$V_{GS} = -5V/20V$	$T_J = 150\text{ }^{\circ}\text{C}$	—	5	—
$E_{off}$	Turn-off energy		$V_{Bus} = 600V$ $I_D = 250A$ $R_{GON} = 1.6\Omega$ $R_{GOFF} = 0.9\Omega$	$T_J = 150\text{ }^{\circ}\text{C}$	—	4.5	—
$R_{Gint}$	Internal gate resistance			—	1.18	—	$\Omega$
$R_{thJC}$	Junction-to-case thermal resistance			—	—	0.086	$^{\circ}\text{C}/\text{W}$

The following table lists the body diode ratings and characteristics (per SiC MOSFET) of the MSCSM120VR1M062CT6AG device.

**Table 1-4. Body Diode Ratings and Characteristics**

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
$V_{SD}$	Diode forward voltage	$V_{GS} = 0V; I_{SD} = 200A$		—	4	—	V
		$V_{GS} = -5V; I_{SD} = 200A$		—	4.2	—	
$t_{rr}$	Reverse recovery time	$I_{SD} = 200A$		—	90	—	ns
$Q_{rr}$	Reverse recovery charge			—	2750	—	
$I_{rr}$	Reverse recovery current	$V_R = 800V$ $di_F/dt = 5000\text{ A}/\mu\text{s}$		—	68	—	A

**1.2****SiC Diode Ratings and Characteristics (Per SiC Diode)**

The following table lists the SiC diode ratings and characteristics of the MSCSM120VR1M062CT6AG device.

**Table 1-5. SiC Diode Ratings and Characteristics**

Symbol	Characteristic	Test Conditions		Min.	Typ.	Max.	Unit
$V_{RRM}$	Peak repetitive reverse voltage			—	—	1700	V
$I_{RM}$	Reverse leakage current	$V_R = 1700V$	$T_J = 25\text{ }^{\circ}\text{C}$	—	60	1200	$\mu\text{A}$
			$T_J = 175\text{ }^{\circ}\text{C}$	—	900	—	
$I_F$	Forward current	$T_C = 125\text{ }^{\circ}\text{C}$		—	180	—	A
$V_F$	Diode forward voltage	$I_F = 180\text{A}$	$T_J = 25\text{ }^{\circ}\text{C}$	—	1.5	1.8	V
			$T_J = 175\text{ }^{\circ}\text{C}$	—	2.3	—	
$Q_C$	Total capacitive charge	$V_R = 900V$		—	1380	—	nC
$C$	Total capacitance	$f = 1\text{ MHz}, V_R = 600V$		—	1002	—	pF
		$f = 1\text{ MHz}, V_R = 900V$		—	828	—	
$R_{thJC}$	Junction-to-case thermal resistance			—	—	0.1	$^{\circ}\text{C/W}$

## 1.3

**Thermal and Package Characteristics**

The following table lists the thermal and package characteristics of the MSCSM120VR1M062CT6AG device.

**Table 1-6. Thermal and Package Characteristics**

Symbol	Characteristic	Min.	Max.	Unit
$V_{ISOL}$	RMS isolation voltage, any terminal to case t = 1 min, 50 Hz/60 Hz	4000	—	V
$T_J$	Operating junction temperature range	-40	175	°C
$T_{JOP}$	Recommended junction temperature under switching conditions	-40	$T_{Jmax}-25$	
$T_{STG}$	Storage case temperature	-40	125	
$T_C$	Operating case temperature	-40	125	
Torque	Mounting torque	To heatsink For terminals	M6 M5	3 2
Wt	Package weight	—	300	g

The following table lists the temperature sensor NTC of the MSCSM120VR1M062CT6AG device.

**Table 1-7. Temperature Sensor NTC**

Symbol	Characteristic	Min.	Typ.	Max.	Unit
$R_{25}$	Resistance at 25 °C	—	50	—	kΩ
$\Delta R_{25}/R_{25}$	—	—	5	—	%
$B_{25/85}$	$T_{25} = 298.15K$	—	3952	—	K
$\Delta B/B$	—	$T_C = 100 °C$	4	—	%

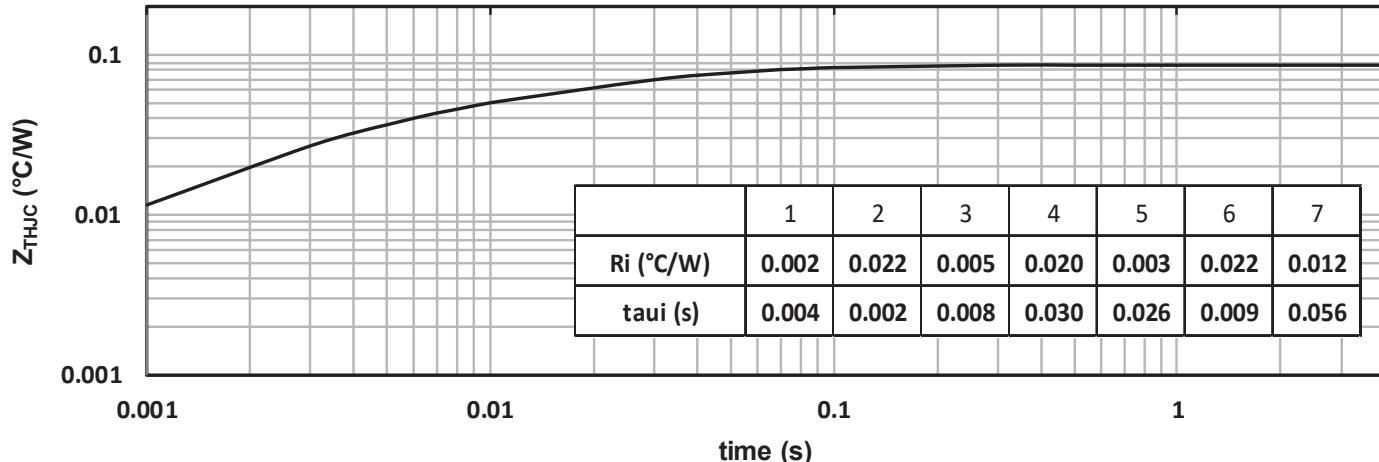
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]} \quad T: \text{Thermistor temperature} \\ R_T: \text{Thermistor value at } T$$

**Note:** See [APT0406—Using NTC Temperature Sensor Integrated into Power Module](#) for more information.

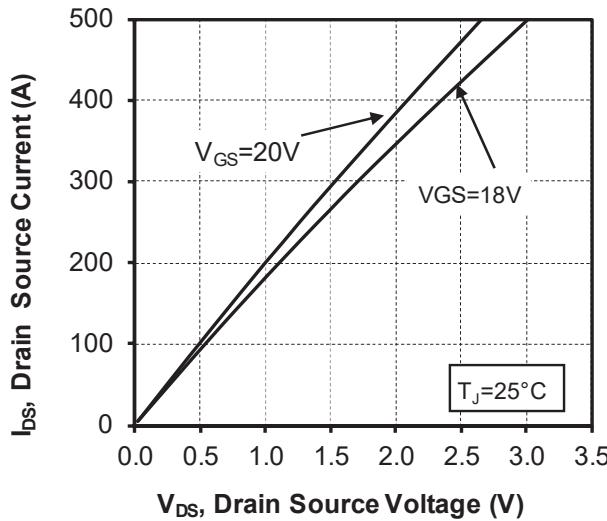
## 1.4 Typical SiC MOSFET Performance Curve

The following figures show the SiC MOSFET performance curves of the MSCSM120VR1M062CT6AG device.

**Figure 1-1. Maximum Thermal Impedance**



**Figure 1-2. Output Characteristics,  $T_J = 25^{\circ}\text{C}$**



**Figure 1-3. Output Characteristics,  $T_J = 175^{\circ}\text{C}$**

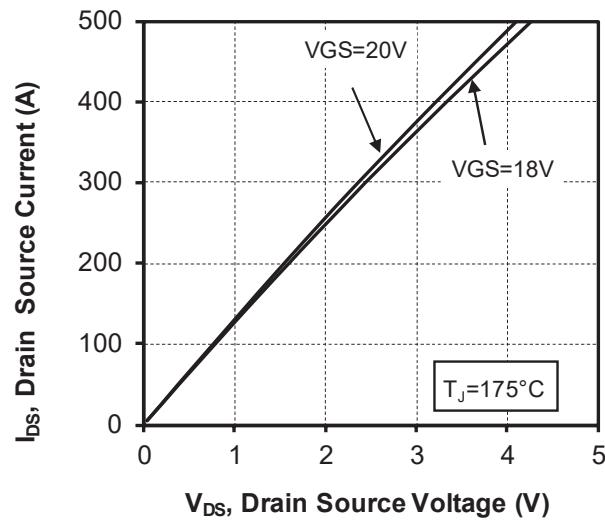


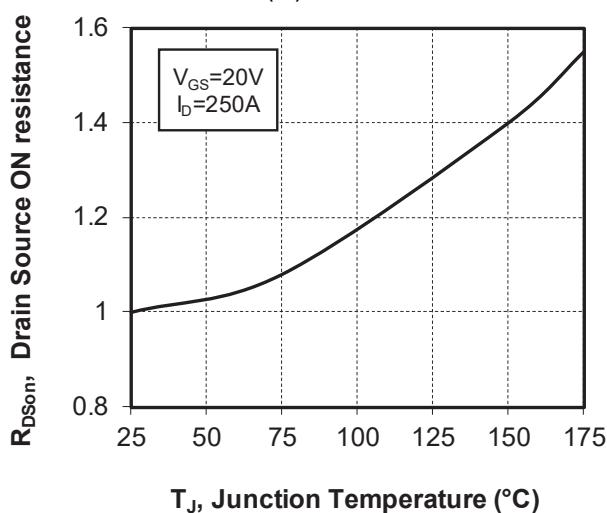
Figure 1-4. Normalized  $R_{DS(on)}$  vs. Temperature

Figure 1-5. Transfer Characteristics

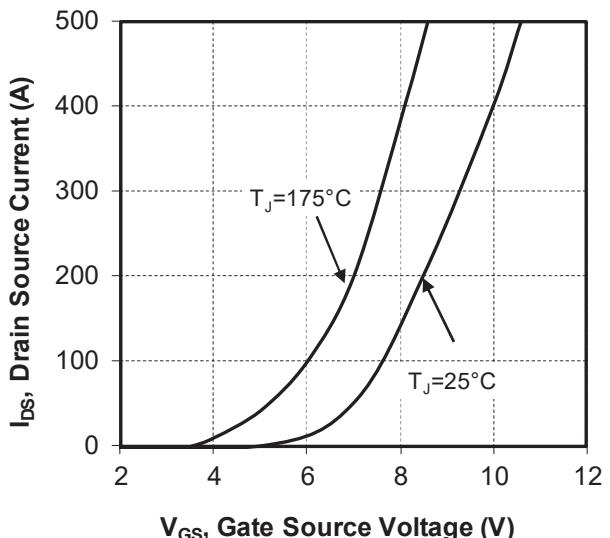
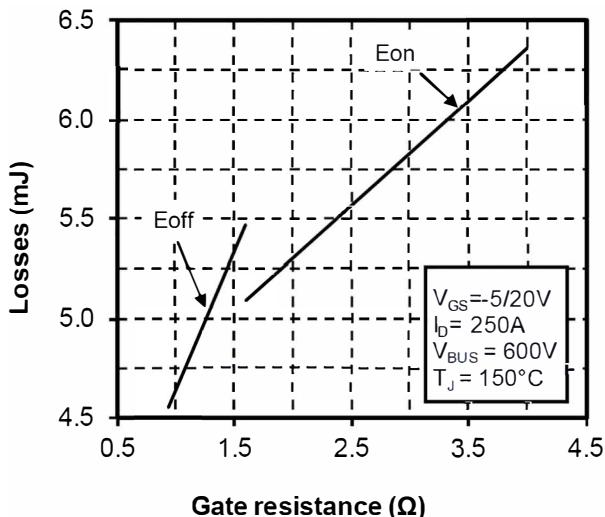
Figure 1-6. Switching Energy vs. R<sub>g</sub>

Figure 1-7. Switching Energy vs. Current

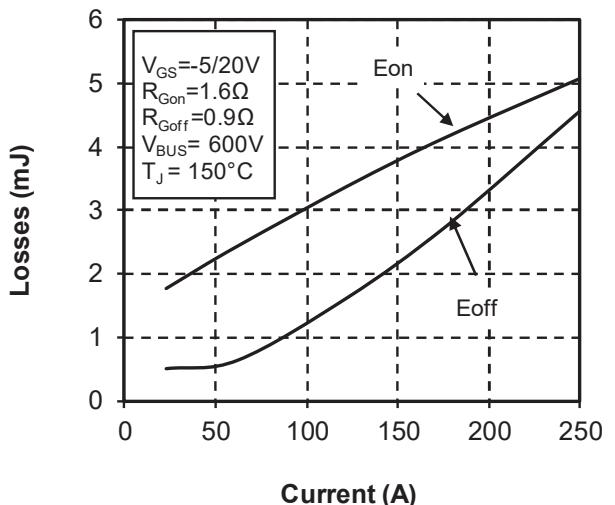


Figure 1-8. Capacitance vs. Drain Source Voltage

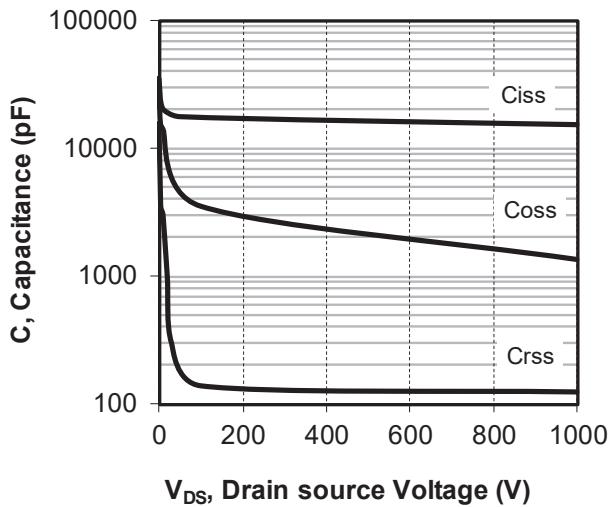
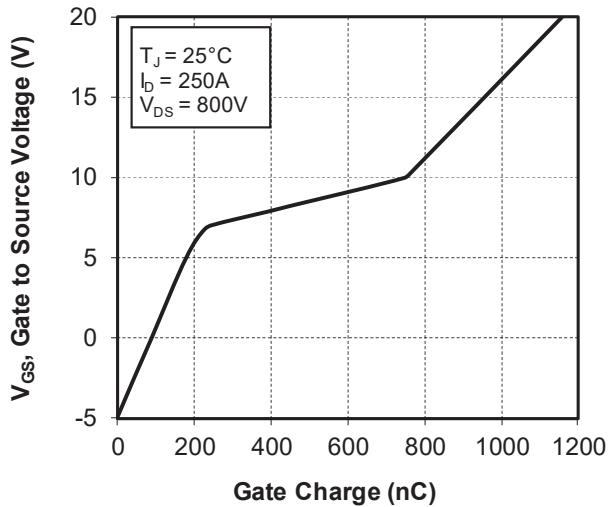
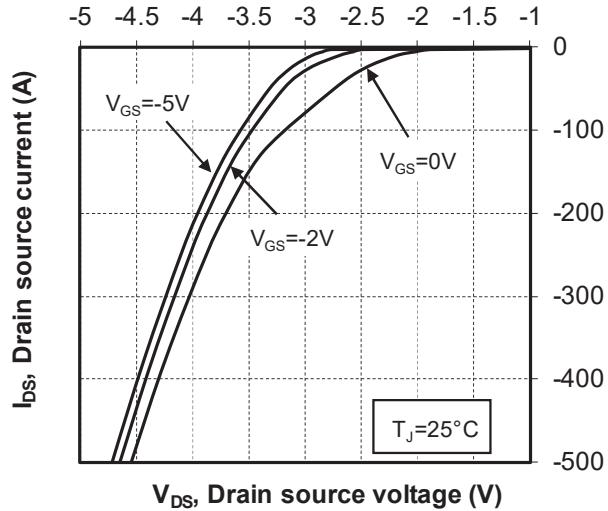
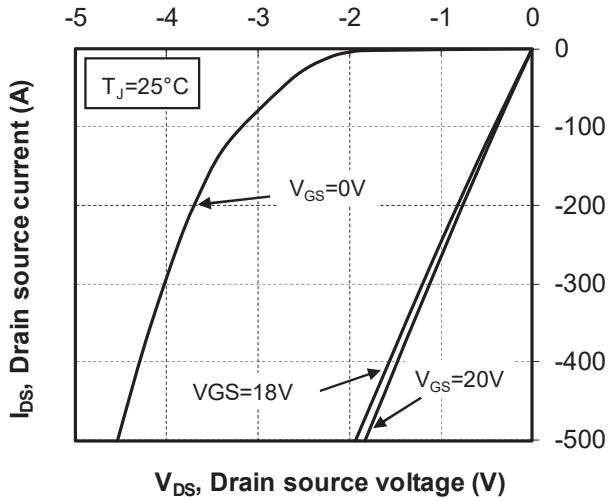
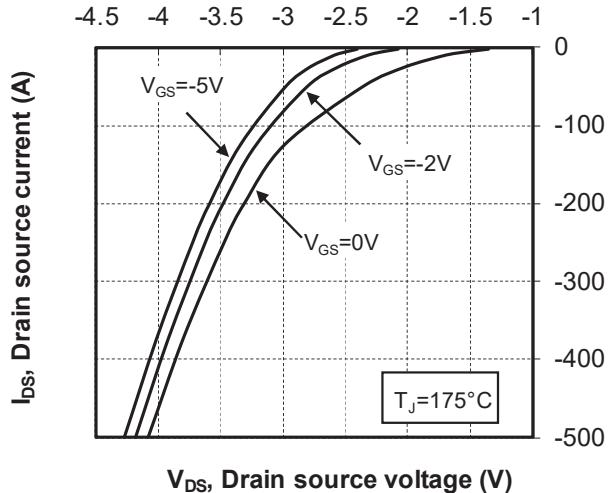
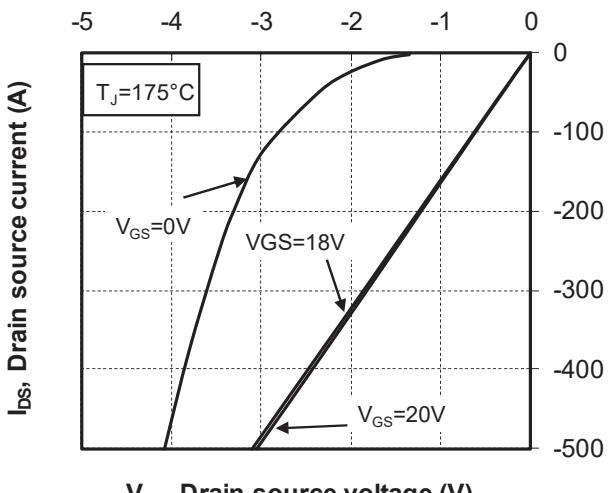
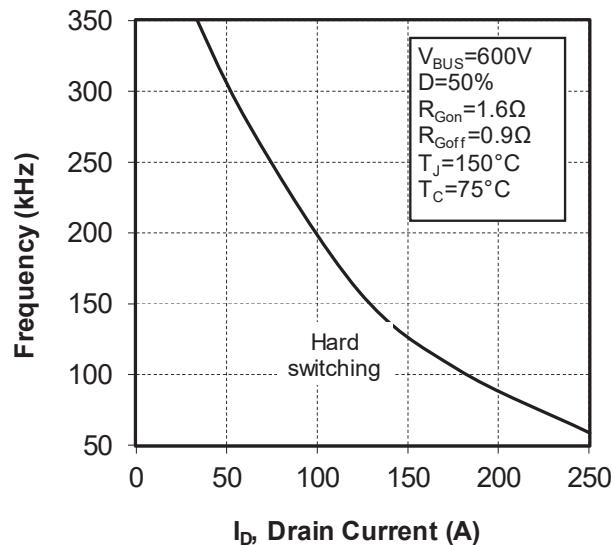


Figure 1-9. Gate Charge vs. Gate Source Voltage

Figure 1-10. Body Diode Characteristics,  $T_J = 25^\circ\text{C}$ Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics,  $T_J = 25^\circ\text{C}$ Figure 1-12. Body Diode Characteristics,  $T_J = 175^\circ\text{C}$ Figure 1-13. 3<sup>rd</sup> Quadrant Characteristics,  $T_J = 175^\circ\text{C}$ 

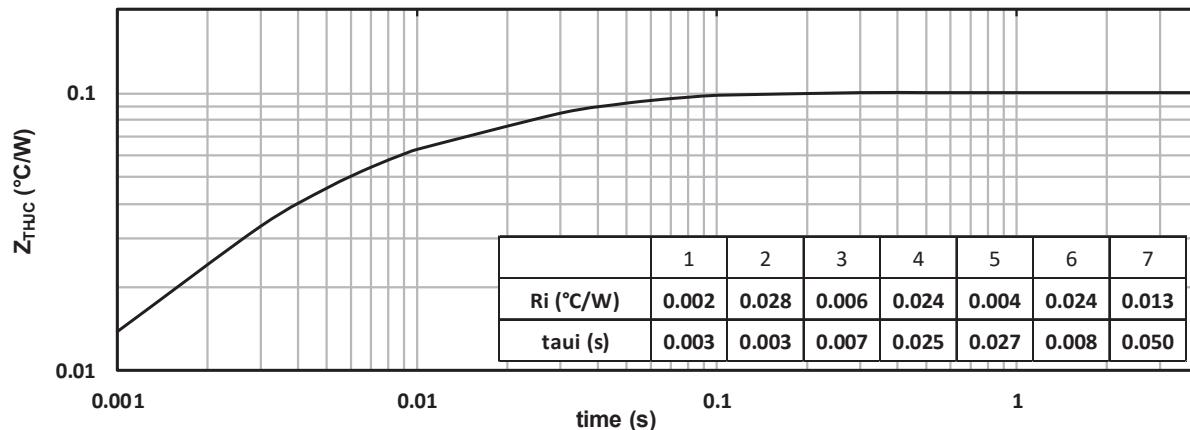
**Figure 1-14. Operating Frequency vs. Drain Current**



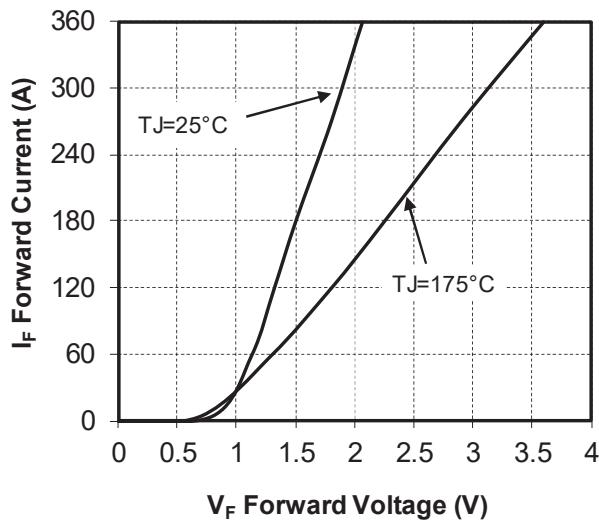
## 1.5 Typical SiC Diode Performance Curve

The following figures show the SiC diode performance curves of the MSCSM120VR1M062CT6AG device.

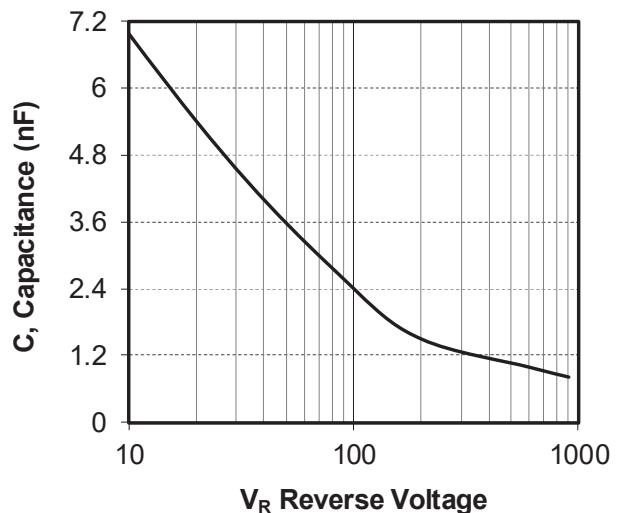
**Figure 1-15. Maximum Thermal Impedance**



**Figure 1-16. Forward Characteristics**



**Figure 1-17. Capacitance vs. Reverse Voltage**



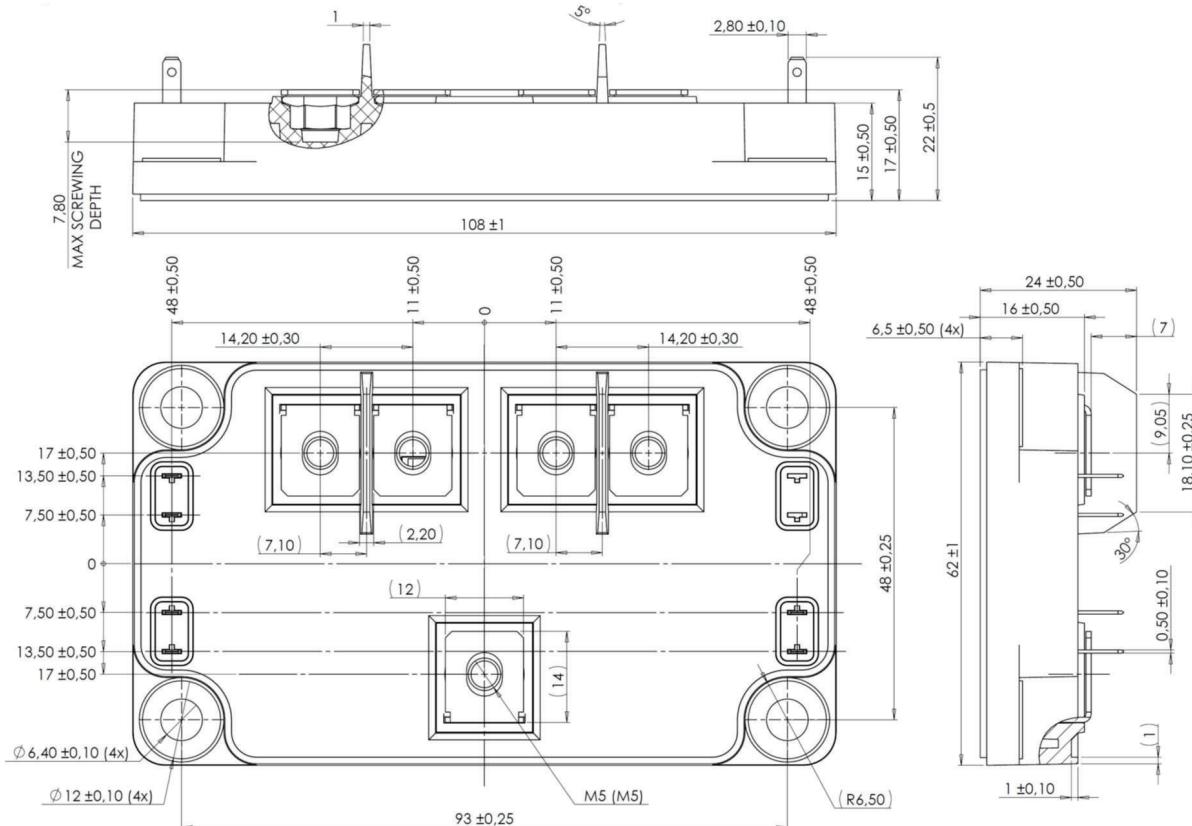
## 2. Package Specifications

The following section shows the package specification of the MSCSM120VR1M062CT6AG device.

### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120VR1M062CT6AG device. The dimensions in the following figure are in millimeters.

**Figure 2-1. Package Outline Drawing**



**3. Revision History**

Revision	Date	Description
A	08/2022	Initial Revision

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